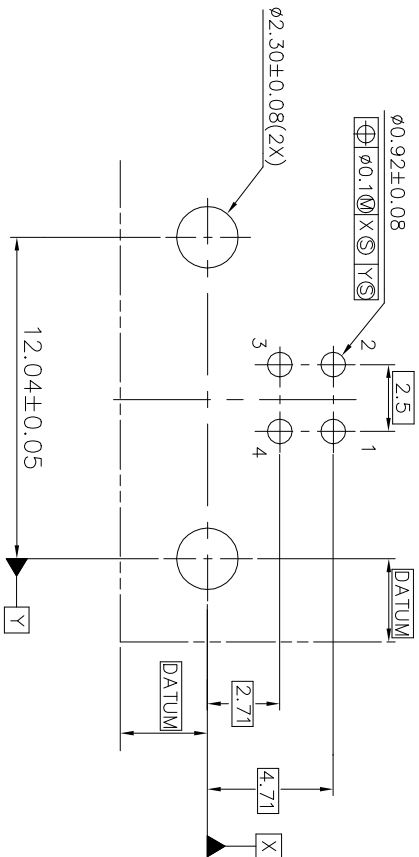
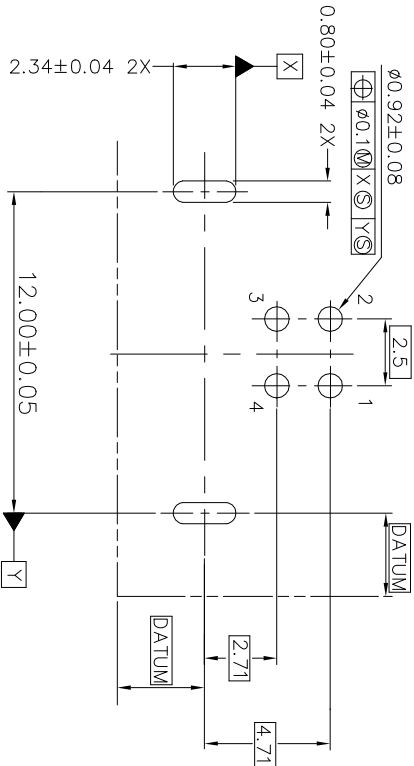




P.C. BOARD LAYOUT

STYLE 1 APPLY FOR TYPE 1 & 2



P.C. BOARD LAYOUT

STYLE 2 APPLY FOR TYPE 3

NOTES:

1. MATERIAL:

SHIELD & CONTACTS: COPPER ALLOY
HOUSING: UL 94V-0 ,HIGH TEMPERATURE THERMOPLASTIC.
COLOR: SEE PRODUCT NUMBER CODE.

2. PLATING: SEE PRODUCT NUMBER CODE.

SHIELD: BRIGHT TIN, NICKEL UNDERPLATE(USED FOR WAVE SOLDER PROCESS),
PLATING NICKEL ONLY(USED FOR PIP PROCESS).

3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER

4. RECOMMENDED BOARD THICKNESS IS 1.57 mm (.062)

5. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S

6. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

7. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C
PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR
PHASE REFLOW OVEN.

8. THE PART CAN BE USED FOR PIP PROCESS.

mat'l. code				surface	tolerance	projection	product family		
				ISO 1302 ✓	ISO 406 ISO 1101		HPL 511 USB2.0		
ltr	ecn	no	dr	date	tolerances unless otherwise specified			title	
					angular	0.0±0.30	mm	USB RECEPTACLE B TYPE	
					linear	0.00±0.20			
Y					0±2°	0.000±0.10	scale 1:1		
					dr	laurence.Zang	02/26/19	dwg no	
						enq	laurence.Zang	02/26/19	61729
						chr	Tim. Yao	02/26/19	A3
						apdd	Tim. Yao	02/26/19	
sheet revision								type	Product Customer Drawing
index	sheet								